



Ceramic High Power

▶ 3535 1.8t Series

UV (275nm)

# PRODUCT DATASHEET



N0Q52S92Z





# **APPLICATIONS:**

- Industrial Curing
- Counterfeit Detection
- Medical Device
- Fluorochemistry
- Bacterial Identification
- Cosmetology
- Magnetic Particle Inspection
- Clean Room Inspection
- Mineralogy

3535 1.8t Series



# FEATURES:

- Package: Ceramic SMT Package with Glass Lens
- Forward Current: 40mA
- Forward Voltage (typ.): 6.0V
- Radiant Power (typ.): 4.0mW@40mA
- Colour: Ultraviolet (UV)
- Wavelength: 275nm
- Viewing angle: 120°
- Materials:
  - Die: InGaN
  - Resin: Glass (Water Clear)
  - L/F: Ceramic
- Operating Temperature: -10~+45°C
- Storage Temperature: -10~+50°C
- Grouping parameters:
  - Forward Voltage
  - Radiant Power
  - Peak Wavelength
- Soldering methods: IR Reflow soldering
- MSL: Level 3 according to J-STD020
- Packing: 12mm tape with min. 100pcs/reel, ø180mm (7")





## Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Maximum Forward Current	Imax	100	mA
Pulse Current Width=100µs Duty 1/10	IP	120	mA
Junction Temperature	Tj	50	°C
Power Dissipation	RD	0.6	W
Operating Temperature	Topr	-10~+45	°C
Storage Temperature	Tstg	-10~+50	°C
Solder Temperature	T <sub>SOL</sub>	260 for 10sec	°C

# Electrical & Optical Characteristics (Ta=25°C)

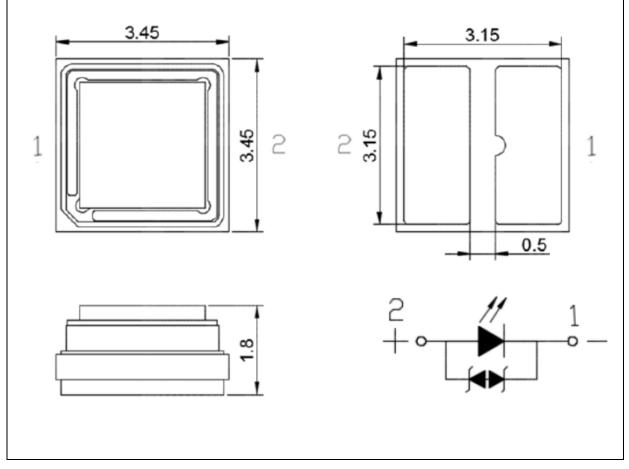
Parameter	Symbol	Values			Unit	Test
		Min.	Тур.	Max.	Onit	Condition
Forward Voltage	VF		6.0		V	I⊧=40mA
Radiant Power	Po		4.0		mW	I⊧=40mA
Peak Wavelength	Wp		275		nm	I⊧=40mA
Spectrum Half Width	Δλ		10.5		nm	I⊧=40mA
Viewing Angle	20 <sub>1/2</sub>		120		deg	I⊧=40mA

1. Radiant Power ( $P_0$ ) ±10%, Forward Voltage ( $V_F$ ) ±0.2V, Wavelength (nm) ±2nm





### Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance  $\pm 0.13$  mm, unless otherwise noted.

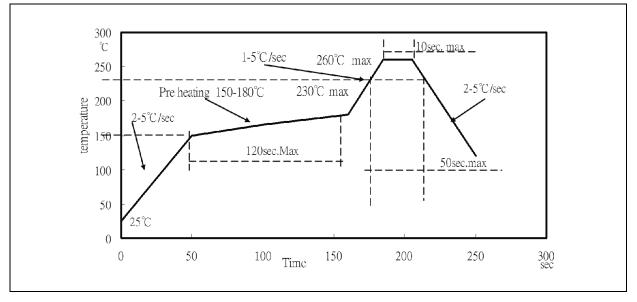
3





**RECOMMENDED SOLDERING PROFILE:** 

#### Lead-free Solder:



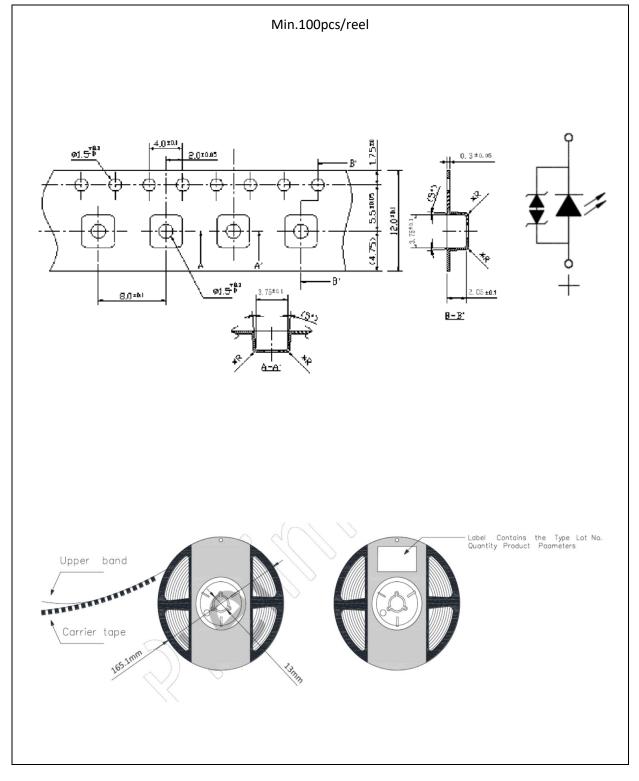
Note:

- 1. Maximum reflow soldering: 2 times.
- 2. Recommended reflow temperature 240°C. Maximum soldering temperature should be limited to 260°C.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.





#### Reel Dimension:



5





#### Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

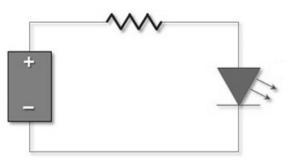
#### Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 65±3°C x 12hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

#### **Testing Circuit:**



Must apply resistor(s) for protection (over current proof).

#### Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

#### ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

6





Version	Date	Summary of Revision
A1.0	24/09/2020	Datasheet set-up.